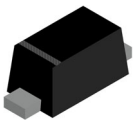
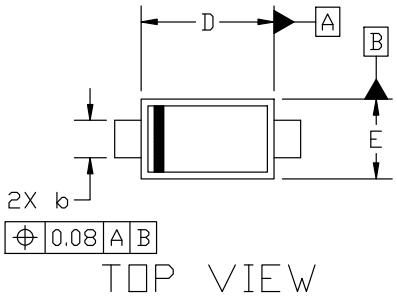
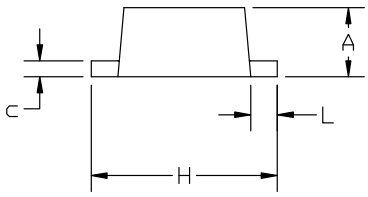


SOD−723, 2−LEAD, 1.00x0.60x0.52
CASE 509AA
ISSUE A

DATE 01 FEB 2024



TOP VIEW



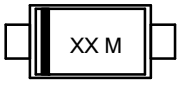
SIDE VIEW

NOTES:

1. DIMENSIONSING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSIONS: MILLIMETER.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

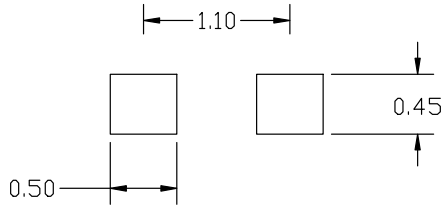
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.49	0.52	0.55
b	0.25	0.28	0.32
c	0.08	0.12	0.15
D	0.95	1.00	1.05
E	0.55	0.60	0.65
H	1.35	1.40	1.45
L	0.15	0.20	0.25

GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

*For additional formation on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	**SOD−723, 2−LEAD, 1.00x0.60x0.52**		**PAGE 1 OF 1**